

**Preliminary Amendment**

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Title: METHOD FOR APPLYING REWIRING TO A PANEL WHILE COMPENSATING FOR POSITION ERRORS OF SEMICONDUCTOR CHIPS IN COMPONENT POSITIONS OF THE PANEL

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**IN THE ABSTRACT**

Please replace the Abstract with the following rewritten paragraph:

Abstract

**METHOD FOR APPLYING REWIRING TO A PANEL WHILE COMPENSATING  
FOR POSITION ERRORS OF SEMICONDUCTOR CHIPS IN COMPONENT  
POSITIONS OF THE PANEL**

**Abstract**

The invention relates to a method for applying rewiring (1) to a panel (2). For this purpose, a panel (2) is provided which has a coplanar overall upper side (16) of an upper side of a plastic compound and the upper sides of semiconductor chips (3). The method provides a rewiring layer with implementation of external contacts (8) and rewiring lines (10) which, by means of a two-stage exposure step, compensates for position errors of the semiconductor chips (3) in the component positions (4) of the panel (2).

{Figure 1}